

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Texas Instruments, et al.

Docket No: TI-26239.1

Serial No: 10/612,129

Examiner: Cao, Phat X.

Filed: 7/2/2003

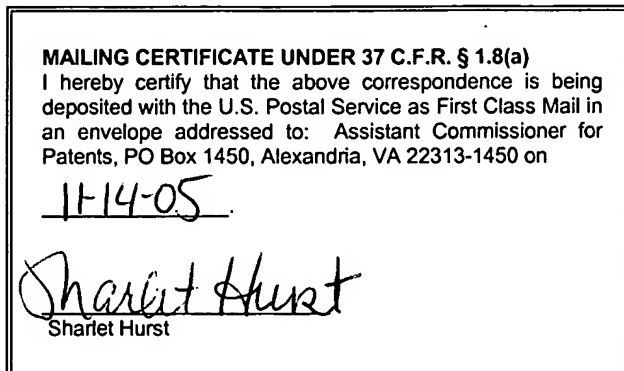
Art Unit: 2814

For: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97 & 1.98

Assistant Commissioner for Patents
Washington, DC 20231

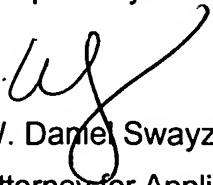
Dear Sir:



Applicants wish to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO-1449. A copy of the noted references is enclosed herewith.

Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668, and please credit any excess fees to such Deposit Account. Any further necessary extension of time is hereby requested.

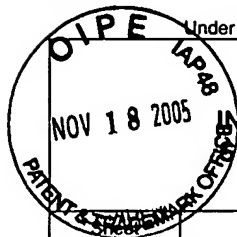
Respectfully submitted,


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Substitute for Form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Complete If Known

Application Number	10/612,129
Filing Date	7/2/2003
First Named Inventor	Yew
Group Art Unit	2814
Examiner Name	Cao, Phat X.
Attorney Docket No.	TI-26239.1

U.S. PATENT DOCUMENTS

Exam. Initials*	Cite No. ¹	U.S. Patent Document		Name of Patentee or Applicant of Cited Doc.	Date of Pub. of Cited Doc. (mm-dd-yyyy)	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number	Kind Code ² (if known)			
	AA	5,739,585		Akram, et al.	04-14-1998	
	AB	5,753,974		Masukawa	05-19-1998	
	AC					
	AD					
	AE					
	AF					
	AG					
	AH					
	AI					
	AJ					

FOREIGN PATENT DOCUMENTS

Exam. Initials*	Cite No. ¹	Foreign Patent Document			Name of Patentee or Applicant of Cited Doc.	Date of Pub. of Cited Doc. (mm-dd-yyyy)	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Office ³	Number ⁴	Kind Code ² (if known)				
	BA	EP	0 810 655 A2		Goh	12-03-1997		
	BB	DE	19712551A1		Kim	11-20-1997		
	BC							
	BD							
	BE							
	BF							
	BG							
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹Unique citation designation number. ²See attached Kinds of U.S. Patent Documents. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3).

⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶Applicant is to place a check mark here if English language Translation is attached.

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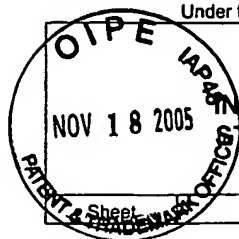


PTO/SB/08A (08-00)

Approved for use through 10/31/2002. OMB 0651-

Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

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Complete If Known

Application Number	10/612,129
Filing Date	7/2/2003
First Named Inventor	Yew
Group Art Unit	2814
Examiner Name	Cao, Phat X.
Attorney Docket No.	TI-26239.1

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Exam. Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
	CA	MATIZENZO L J, et al. "Adhesion Issues in Electronic Packaging". Solid State Technology, Cowan Publ. Corp. Port Washington, NY US vol. 38, no. 7 July 1, 1995 pages 99-100, 102. XP000523397 ISSN: 0038-111X	
	CB	AMAGAI M, et al. "The Effect of Polyimide Surface Morphology and Chemistry on Package Cracking Induced by Interfacial Delamination". Reliability Physics Symposium, 1994, New York, NY USA, IEEE, April 11, 1994, pages 101-107. XP010117230 ISBN: 0-7803-1357-7	
	CC	IWABUCHI KAORU. "Semiconductor Device". Patent Abstracts of Japan. Vol. 1997, no. 06, June 30, 1997 & JP 09 036167 A (SONY CORP), February 7, 1997	
	CD	KIN ZAISHUN. "Semiconductor Package of Chip Scale and its Manufacture". Patent Abstracts of Japan. Vol. 1998, no. 09, July 31, 1998 & JP 10 098130 A, (SAMSUNG ELECTRON CO LTD), April 14, 1998.	
	CE		
	CF		
	CG		
	CH		
	CI		
	CJ		

Examiner Signature		Date Considered	
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